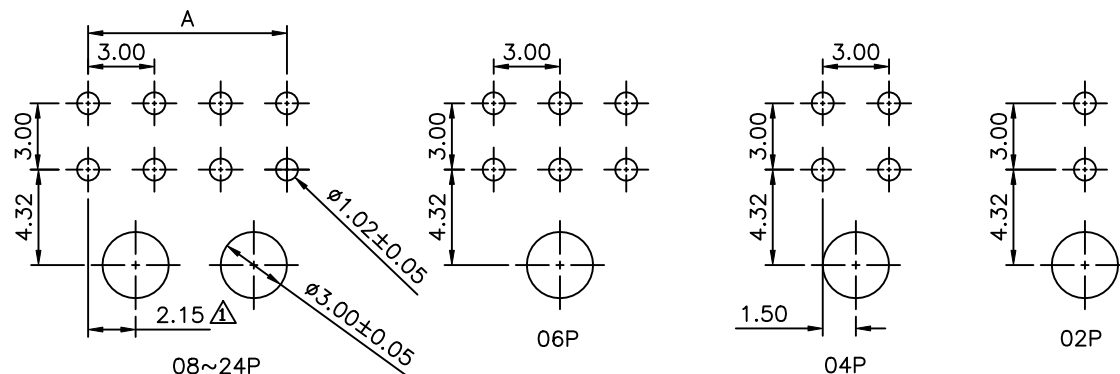
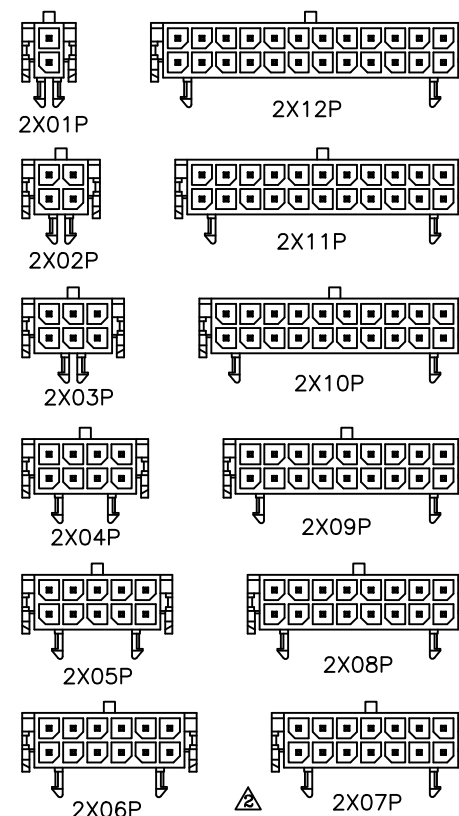
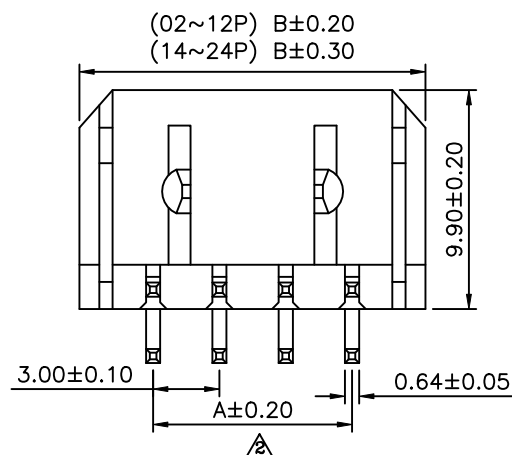
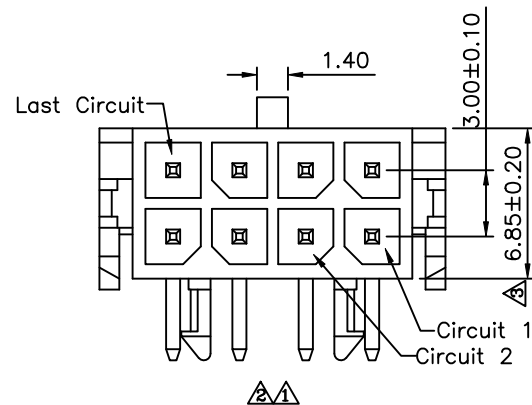




Recommended P.C.B. Layout



SPECIFICATION

1.General Characteristics

3.0mm Micro-Fit Wafer 2XXX DIP 90° With Post Black Insulator Tin Plated

2.Material&Finish

Insulator:PA66+15%G.F.(UL94V-0),Black
Contact:Brass,Tin Plated

3.Electrical Characteristics

Current Rating:5A AC/DC
Voltage Rating:250V AC/DC
Withstanding Voltage:1500V AC/Minute
Contact Resistance:20 Milliohms Max.
Insulation Resistance:1000 Megaohms Min.

4.Environmental Characteristics

Temperature Range:-25°C~+85°C

5.RoHS Compliant

MIF 2 X XX P RP - H
(1) (2) (3) (4) (5) (6)

- (1) MIF:3.0mm Micro-Fit Series
(2) 2: Dual Row
(3) XX: No. Of Position/Per Row
(4) P: Male
(5) RP: DIP Right Angle With Post
(6) H: RoHS Compliant

Pin	A	B
02	—	6.65
04	3.00	9.65
06	6.00	12.65
08	9.00	15.65
10	12.00	18.65
12	15.00	21.65
14	18.00	24.65
16	21.00	27.65
18	24.00	30.65
20	27.00	33.65
22	30.00	36.65
24	33.00	39.65

AUK A MEMBER OF AUK GROUP
太聯事業股份有限公司
AUK CONTRACTORS CO., LTD.

CATEGORY

APPROVED BY

MEI

PART No.

CHECKED BY

HZF

DRAWING No.

DRAWING BY

CYP

SCALE

NONE

REV.

A3

UNLESS OTHERWISE
SPECIFIED
TOLERANCES ARE
X ±0.30
Y ±0.25
Z ±0.20
ANG. ±1°

UNIT

mm

NO. REV. A3
A2
A1
A0

Modify Dim.
Modify Data
Modify Data
NEW RELEASE

HZF 04/13/2018
HZF 09/28/2017
HZF 08/28/2013
HZF 11/16/2011

REVISIONS

CHK

DATE